

AMENDMENTS TO THE CLAIMS

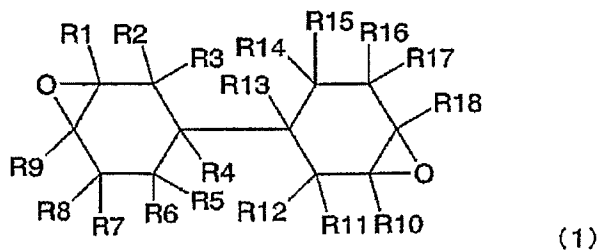
1. (Currently amended) A thermosetting resin composition comprising 100 parts by weight of an epoxy composition (E) and 0.01 to 20 parts by weight of a cationic polymerization initiator (C) is a compound that forms a cationic compound as a result of heating so as to initiate polymerization, and 1 to ~~50 parts~~ 11.1 parts by weight of an epoxy-containing acrylic resin (D) different from components (A) and (B) to 100 parts by weight of the epoxy composition (E),

wherein the epoxy-containing resin (D) includes a polymerization inhibitor and wherein the epoxy-containing resin (D) is prepared by polymerizing an epoxy-containing monomer including compounds each having a glycidyl group or a terminal epoxy group analogous to the glycidyl group and wherein the epoxy group content of the epoxy-containing acrylic resin (D) is 4% to 12%, in terms of oxirane oxygen content,

the epoxy composition (E) comprising 10 to 99 percent by weight of an ester-free alicyclic epoxy compound (A) having two alicyclic epoxy groups and no ester bond per molecule; and 90 to 1 percent by weight of another epoxy compound (B) differing from the epoxy compound (A), the total of (A) and (B) being 100 percent by weight.

2. – 3. (Cancelled)

4. (Previously Presented) The thermosetting resin composition of claim 1 or claim 8, wherein the ester-free alicyclic epoxy compound (A) is an epoxy compound represented by Structural Formula (1):



wherein R1, R2, R3, R4, R5, R6, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, R17, and R18 may be the same as or different from one another and are each hydrogen atom, a halogen atom, a hydrocarbon group which may comprise oxygen atom or a halogen atom, or a substituted or unsubstituted alkoxy group.

5. – 6. (Cancelled)

7. (Previously Presented) An optically transparent material prepared by thermally curing the thermosetting resin composition of claim 1.

8. (Previously Presented) The thermosetting resin composition of claim 1, wherein the epoxy-containing acrylic resin (D) further comprises hydroxyl group in addition to epoxy group.